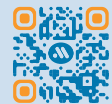
micross
one source. one solution.®

Test Solutions
Environmental & Electrical

Service Overview

Micross' core engineering and manufacturing strengths provide advanced solutions in areas such as electrical test and specialty packaging, as well as component, board and reliability qualification testing, services and solutions.



LIFE-CYCLE TEST SOLUTIONS

- Three Expansive Test Floors
- More than 30 AT Platforms
- Peripheral Engineering and Production Equipment
- Equipment is Available to Rent for Developing Test Programs and Next-Generation Products
- In-House Test Engineers Develop Prototype, Characterization and Production Test Programs for External Customers
- ATE-ATE Program Conversions Support Cost Reduction or End-of-Life Needs
- Production Solutions Including Drop Ship and Inventory Management

HIGH-SPEED, HIGH-DENSITY SOLUTIONS

Our in-house test engineering and hardware design teams are very experienced in developing production-ready solutions for high-speed digital and RF devices such as network processors, transmitters, receivers and line drivers.

For wafer sort, we design vertical probe cards and develop programs for RF devices running as fast as 6GHz. Final test solutions include multi-site load board design and assembly, socket selection and program development for high-speed digital ICs running up to 10 GB/s.

INDUSTRY-CERTIFIED QUALITY

- ITAR-Registered, DLA Certified, ISO9001 & AS9100 Certified
- DMEA Trusted Source
- MIL-PRF-38535, Class Q (Full) & V (Test) Certified
- MIL-PRF-38534, Class H Certified
- MIL-STD-883/750, Laboratory Suitability Certified
- ANSI/ISO/IEC Standard 17025:2005

FULLY-CONFIGURED ATE PLATFORMS

- Advantest 93K: Single Density, Pin Scale, Port Scale, Small Scale
- Credence: D10, Fusion CX, Octet, Quartet, Valstar

PERIPHERAL EQUIPMENT

- Seiko-Epson: 8040
- Synax: SX1211, SX1701N, SX3100
- TSK: UF200, UF3000EX, UF3000EX-Cold
- High Speed Oscilloscopes
  - 26.5GHz PNA-X
  - 67GHz PNA-X
- Temperature Forcing Units

Leader in Hi-Rel Qualification Testing

ENGINEERING EXPERTISE

- Vector Generation
- ATPG
- Wafer Probe Hardware Design
- Final Test Hardware Design
- ATE-ATE Conversion
- Device Characterization
- Final Test
- Hardware Design & Build
- Product Engineering
- Prototype Analysis
- RMA Evaluation
- Test Engineering
- Test Program Development
- Wafer Sort
- Yield Analysis

SPECIALTY ASSEMBLY

- Vector Generation
- Ceramic
- Flip-Chip
- Hermetic
- MCM
- Micro BGA
- SIP
- SoC
- Stacked Die

CONVENTIONAL RELIABILITY

- Autoclave
- Ball/Die Shear
- Constant Acceleration
- EFR Analysis
- ESD
- HAST
- HTOL
- HTS
- Latch-Up
- Mechanical Shock
- Moisture Level
- Preconditioning
- Solderability
- Temperature Cycle
- Thermal Shock
- Torque
- Vibration
- Wire/Die Pull

NEXT-GEN RELIABILITY

- Chamberless Burn-In
- Liquid Burn-In
- System-Level Reference Design
- Thermal-Electrical Cooling

DIGITAL & MIXED SIGNAL

- Microprocessors, DSP, Microcontroller, Graphic Enginers
- Communications (Ethernet, DSL, Base Band, Networking)
- Consumer (Games, Digital Audio, Digital TV, Set Top Box)
- System-On-Chip, High Performance ASICs
- FPGAs, MEMs

MEMORY

- SDRAM, DDR2/3, SRAM, MRAM
- EEPROM, EPROM, Serial Flash

RF TEST SUPPORT

- LTX-CXV
- Verigy Portscale
- 6/8GHz
- Receiver
- Transmitter
- Power Amplifier
- Frequency Generator
- Transceiver
- In Socket De-Embedding (Open, Short, Load and Thru)
- 6GHz Wafer Sort
- Low Jitter Clock Source
- ACPR, EVM, Noise Figure, Power IIP2, IIP3, P1db, Downconvert, Upconvert, PLL, Noise, In Band Spurious, PAE, Turning Curves, RF Frequency, QPSK
- Modulation/Demodulation, I/Q Mod/Demodulation
- Custom Frequency Calibration

RF 10+ GHz CAPABILITY

(Expandable to 80GHz)

- PA LNA, Filter, Mixer, Digital TV
- Wireless LAN, Bluetooth Product Test Program

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